

External_Type	Material_Group	Substances	CAS_Number	Mass	Mass_Percentage_in_Leaf	Massmg
Wire	Pure metal	Aluminium (Al)	7429-90-5	0.01	100.0	0.26
			Subtotal	0.01	100	0.26
Die	Doped silicon	Silicon (Si)	7440-21-3	0.24	100.0	4.8
			Subtotal	0.24	100	4.8
Solder Wire	Lead alloy	Tin (Sn)	7440-31-5	0	5.0	0.05
	Lead alloy	Silver (Ag)	7440-22-4	0	2.5	0.03
	Lead alloy	Lead (Pb)	7439-92-1	0.05	92.5	0.93
	Tin alloy	Tin (Sn)	7440-31-5	0.02	10.0	0.45
	Silver alloy	Silver (Ag)	7440-22-4	0	2.0	0.09
	Lead alloy	Lead (Pb)	7439-92-1	0.2	88.0	3.93
			Subtotal	0.27	200	5.48
Wire	Pure metal	Aluminium (Al)	7429-90-5	0.2	100.0	4
			Subtotal	0.2	100	4
Lead Frame	Copper alloy	Phosphorous (P)	7723-14-0	0.02	0.03	0.4
	Copper alloy	Iron (Fe)	7439-89-6	0.04	0.06	0.8
	Copper alloy	Copper (Cu)	7440-50-8	67.07	99.91	1338.79
			Subtotal	67.13	100	1339.99
Post-plating	Pure metal	Tin (Sn)	7440-31-5	1.04	100.0	20.68
			Subtotal	1.04	100	20.68
Mould Compound		Tetrabromobisphenol A/Epichlorohydrin polymer	40039-93-8	0.22	0.7	4.35
	Polymer	Phenol Formaldehyde resin (generic)	9003-35-4	1.87	6.0	37.26
	Polymer	Epichlorohydrin/Diethyleneglycol Epoxy resin (generic)	25928-94-3	3.73	12.0	74.52
	Filler	Silica fused	60676-86-0	21.78	70.0	434.7
	Carbon Black	Carbon black	1333-86-4	0.09	0.3	1.86
	Filler	Misc. Silica compounds (generic)	14808-60-7	3.11	10.0	62.1
	Flame retardant	Antimony Trioxide (Sb2O3) - cas no. 1309-64-4	1309-64-4	0.31	1.0	6.21
			Subtotal	31.11	100	621
			Total	100	100	1996.21

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